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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|-------------|-----------------------------------|-----------------|-----------------------|
| Applicant: | Zou et al. | Examiner: | Unknown |
| Serial No.: | 10/712,591 | Group Art Unit: | Unknown |
| Filed: | November 13, 2003 | Docket No.: | H0005211 (HON0002/US) |
| For: | METHOD OF PROCESSING SUBSTRATE | | |

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Applicant's duty of disclosure under 37 C.F.R. 1.56. Copies of the articles are enclosed.

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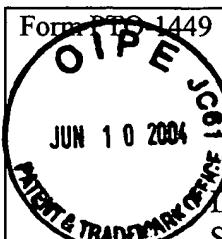
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#12986



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| U.S. Department of Commerce Patent and Trademark Office | | Atty. Docket No. H0005211 (HON0002/US) | Serial No. 10/712,591 |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Applicant Zou et al. | |
| | | Filing Date November 13, 2003 | Group |

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| Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate |
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